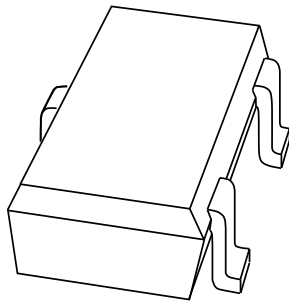


DATA SHEET



BAP50-04W General purpose PIN diode

Product specification

2001 Jan 29



General purpose PIN diode

BAP50-04W

FEATURES

- Two elements in series configuration in a small SMD plastic package
- Low diode capacitance
- Low diode forward resistance.

APPLICATIONS

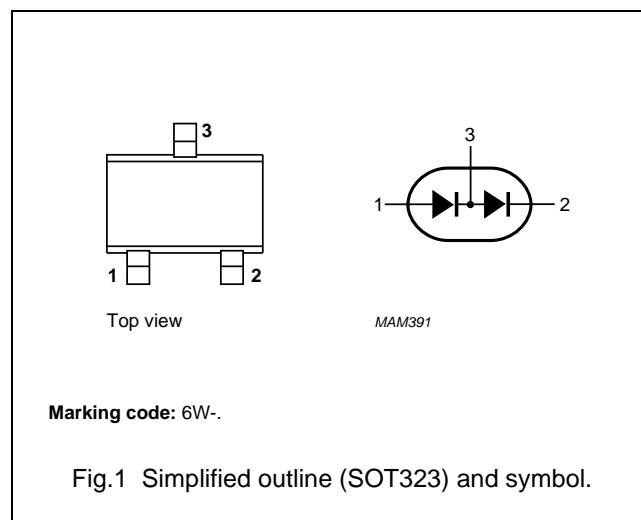
- General RF applications.

DESCRIPTION

Two planar PIN diodes in series configuration in an SOT323 small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	anode
2	cathode
3	common connection



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V_R	continuous reverse voltage		–	50	V
I_F	continuous forward current		–	50	mA
P_{tot}	total power dissipation	$T_s = 90\text{ °C}$	–	240	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–65	+150	°C

General purpose PIN diode

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ELECTRICAL CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per diode						
V _F	forward voltage	I _F = 50 mA	–	0.95	1.1	V
V _R	reverse voltage	I _R = 10 μA	50	–	–	V
I _R	reverse current	V _R = 50 V	–	–	100	nA
C _d	diode capacitance	V _R = 0; f = 1 MHz	–	0.45	–	pF
		V _R = 1 V; f = 1 MHz	–	0.35	0.6	pF
		V _R = 5 V; f = 1 MHz	–	0.30	0.5	pF
r _D	diode forward resistance	I _F = 0.5 mA; f = 100 MHz; note 1	–	25	40	Ω
		I _F = 1 mA; f = 100 MHz; note 1	–	14	25	Ω
		I _F = 10 mA; f = 100 MHz; note 1	–	3	5	Ω
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	–	1.05	–	μs
L _S	series inductance	I _F = 10 mA; f = 100 MHz	–	1.60	–	nH

Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

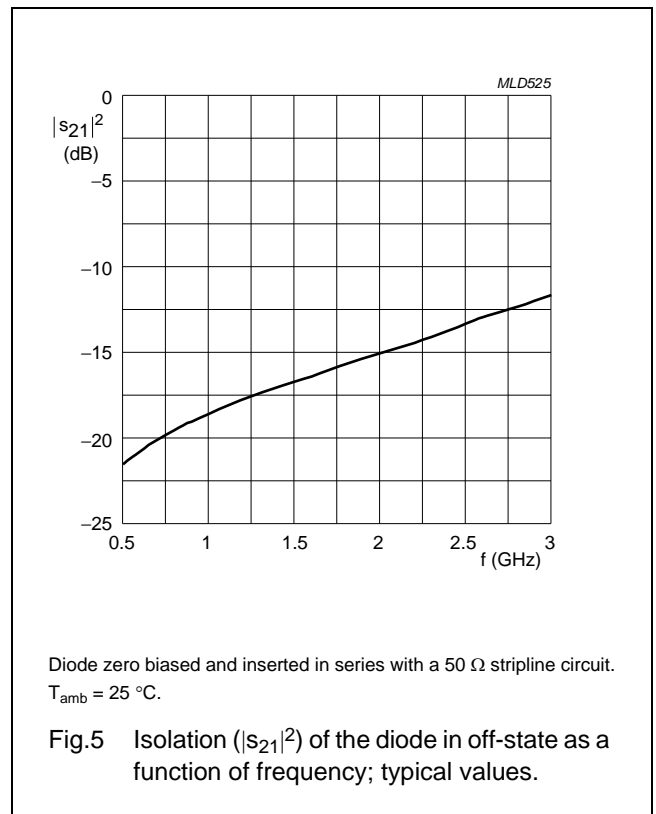
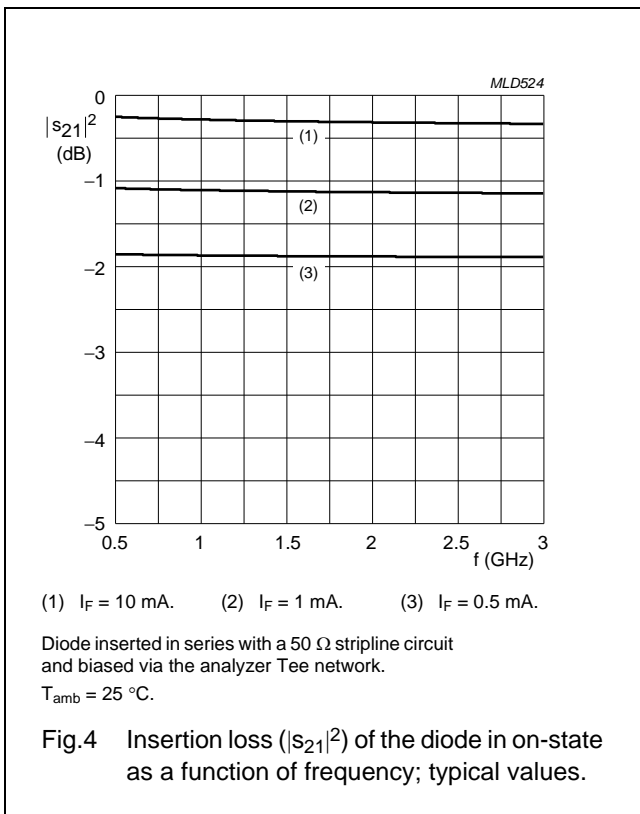
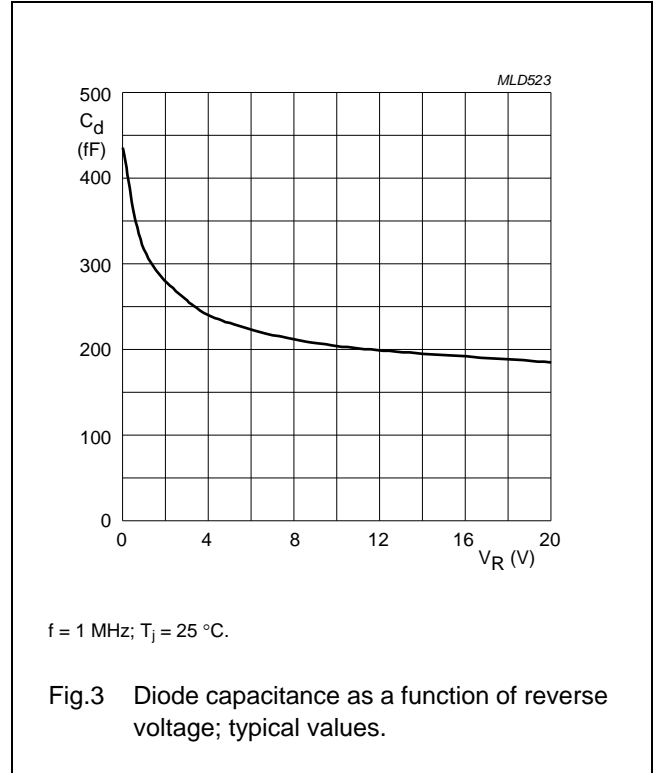
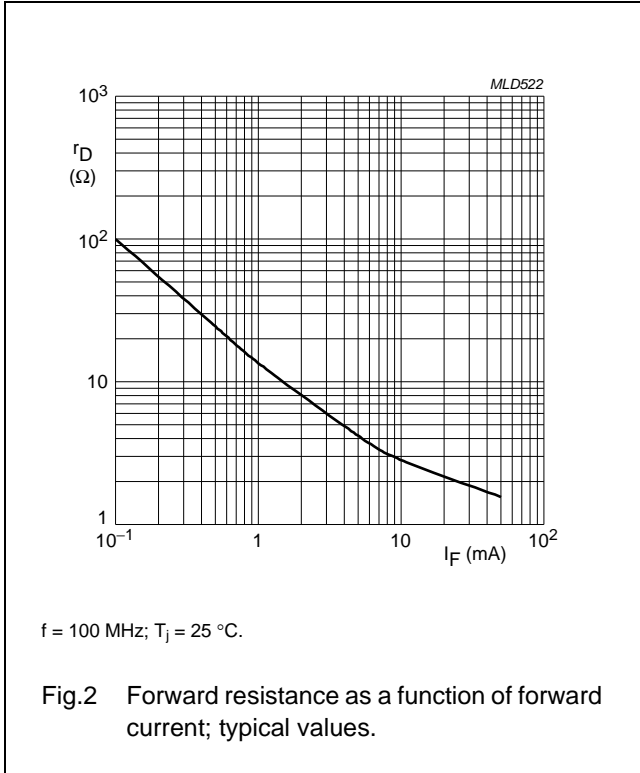
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	250	K/W

General purpose PIN diode

BAP50-04W

GRAPHICAL DATA



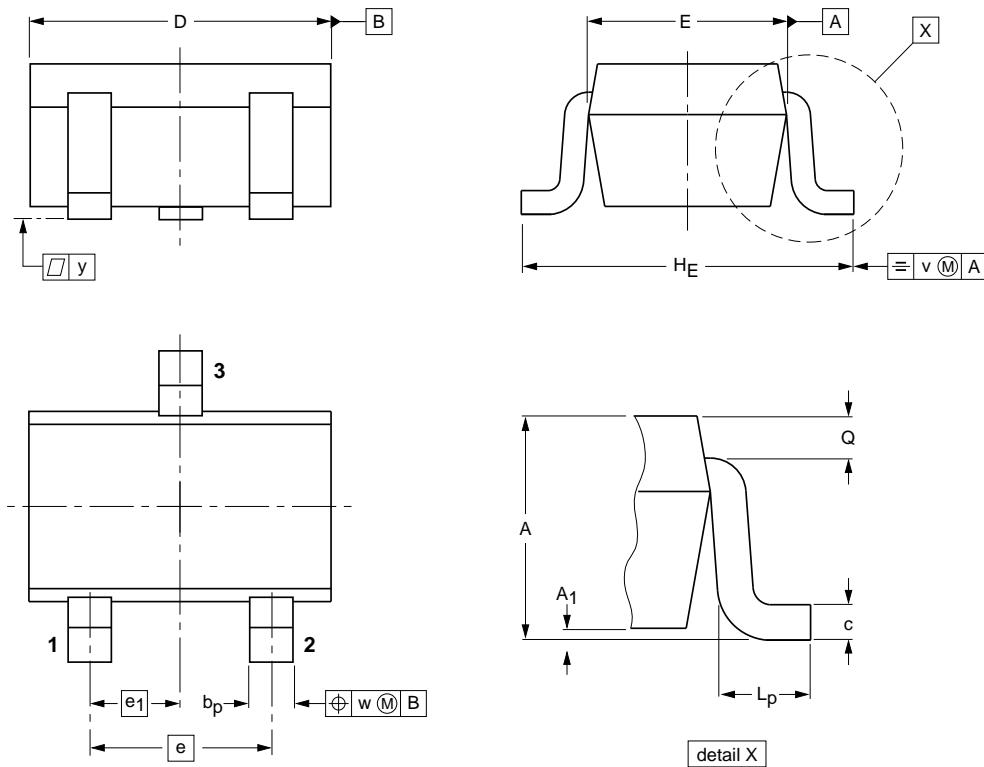
General purpose PIN diode

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PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			04-11-04 06-03-16

General purpose PIN diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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General purpose PIN diode

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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